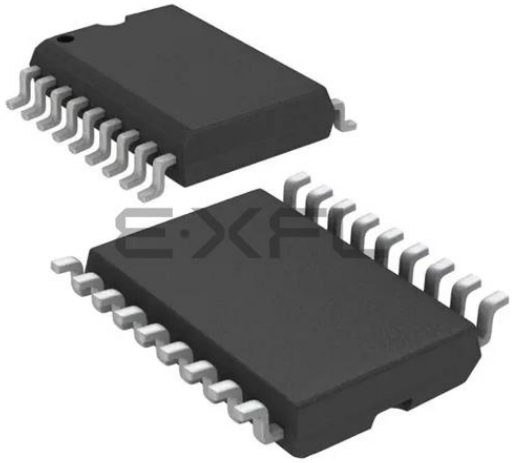

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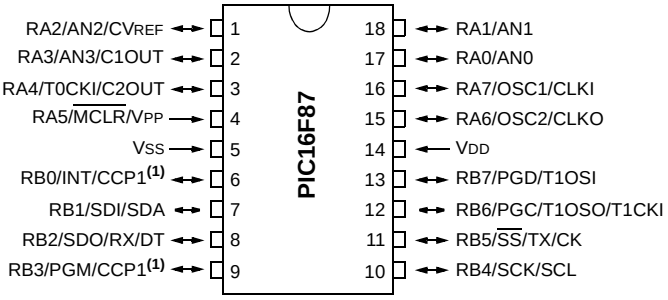
Applications of "Embedded - Microcontrollers"

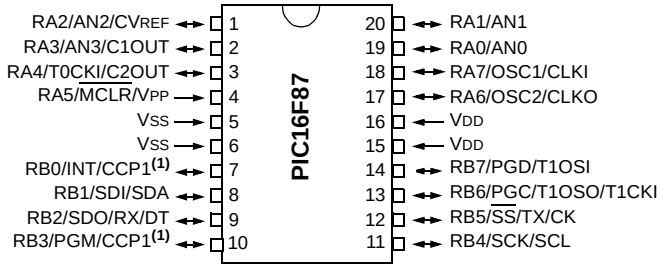
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f88-e-so

Pin Diagrams

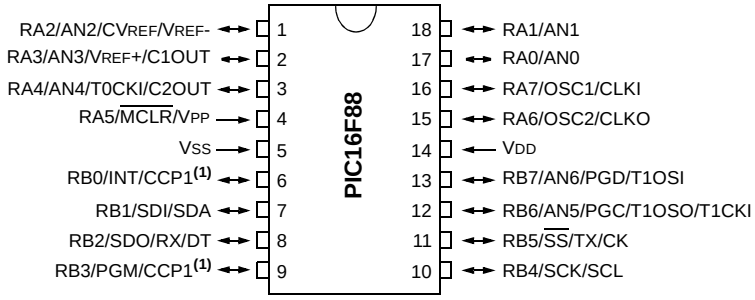
18-Pin PDIP, SOIC



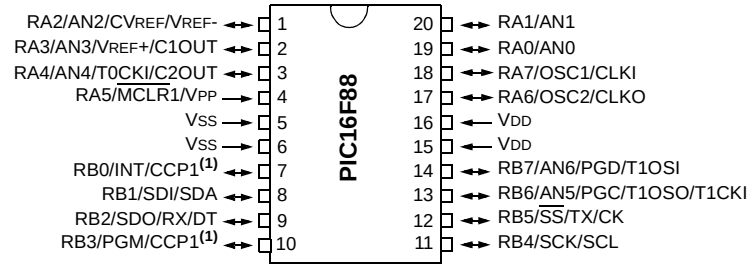
20-Pin SSOP



18-Pin PDIP, SOIC



20-Pin SSOP



Note 1: The CCP1 pin is determined by the CCPMX bit in Configuration Word 1 register.

2.0 MEMORY ORGANIZATION

There are two memory blocks in the PIC16F87/88 devices. These are the program memory and the data memory. Each block has its own bus, so access to each block can occur during the same oscillator cycle.

The data memory can be further broken down into the general purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the "core" are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

The data memory area also contains the data EEPROM memory. This memory is not directly mapped into the data memory but is indirectly mapped. That is, an indirect address pointer specifies the address of the data EEPROM memory to read/write. The PIC16F87/88 device's 256 bytes of data EEPROM memory have the address range of 00h-FFh. More details on the EEPROM memory can be found in **Section 3.0 "Data EEPROM and Flash Program Memory"**.

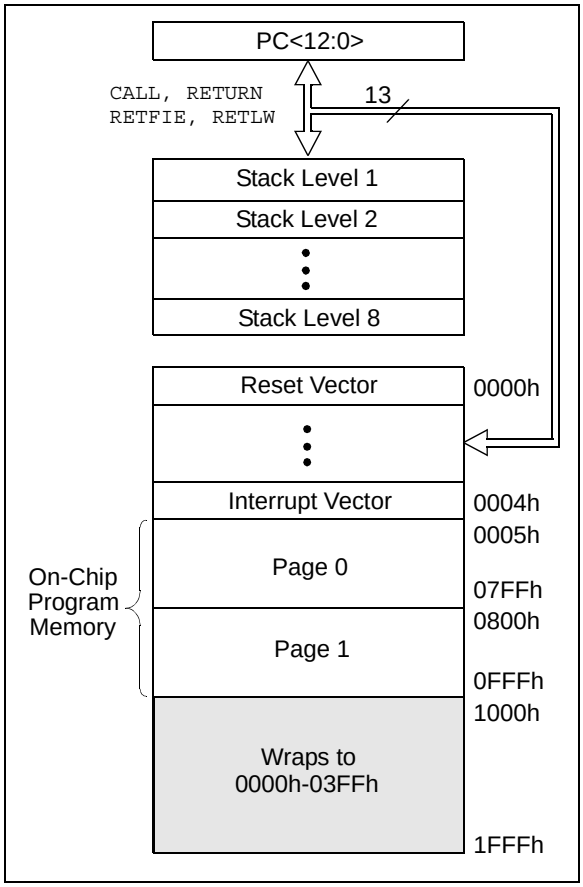
Additional information on device memory may be found in the "*PIC® Mid-Range MCU Family Reference Manual*" (DS33023).

2.1 Program Memory Organization

The PIC16F87/88 devices have a 13-bit program counter capable of addressing an 8K x 14 program memory space. For the PIC16F87/88, the first 4K x 14 (0000h-0FFFh) is physically implemented (see Figure 2-1). Accessing a location above the physically implemented address will cause a wraparound. For example, the same instruction will be accessed at locations 020h, 420h, 820h, C20h, 1020h, 1420h, 1820h and 1C20h.

The Reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK: PIC16F87/88



2.2 Data Memory Organization

The data memory is partitioned into multiple banks that contain the General Purpose Registers and the Special Function Registers. Bits RP1 (STATUS<6>) and RP0 (STATUS<5>) are the bank select bits.

RP1:RP0	Bank
00	0
01	1
10	2
11	3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain SFRs. Some "high use" SFRs from one bank may be mirrored in another bank for code reduction and quicker access (e.g., the STATUS register is in Banks 0-3).

Note:	EEPROM data memory description can be found in **Section 3.0 "Data EEPROM and Flash Program Memory"** of this data sheet.

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Details on page
Bank 2											
100h(2)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	26, 135
101h	TMR0	Timer0 Module Register								xxxx xxxx	69
102h(2)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	135
103h(2)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	17
104h(2)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	135
105h	WDTCON	—	—	—	WDTPS3	WDTPS2	WDTPS1	WDTPS0	SWDTEN	---0 1000	142
106h	PORTB	PORTB Data Latch when written; PORTB pins when read (PIC16F87) PORTB Data Latch when written; PORTB pins when read (PIC16F88)								xxxx xxxx 00xx xxxx	58
107h	—	Unimplemented								—	—
108h	—	Unimplemented								—	—
109h	—	Unimplemented								—	—
10Ah(1,2)	PCLATH	—	—	—	Write Buffer for the Upper 5 bits of the Program Counter					---0 0000	135
10Bh(2)	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	19, 69, 77
10Ch	EEDATA	EEPROM/Flash Data Register Low Byte								xxxx xxxx	34
10Dh	EEADR	EEPROM/Flash Address Register Low Byte								xxxx xxxx	34
10Eh	EEDATH	—	—	EEPROM/Flash Data Register High Byte						--xx xxxx	34
10Fh	EEADRH	—	—	—	—	EEPROM/Flash Address Register High Byte				---- xxxx	34
Bank 3											
180h(2)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	135
181h	OPTION_REG	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	18, 69
182h(2)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	135
183h(2)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	17
184h(2)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	135
185h	—	Unimplemented								—	—
186h	TRISB	PORTB Data Direction Register								1111 1111	58, 83
187h	—	Unimplemented								—	—
188h	—	Unimplemented								—	—
189h	—	Unimplemented								—	—
18Ah(1,2)	PCLATH	—	—	—	Write Buffer for the Upper 5 bits of the Program Counter					---0 0000	135
18Bh(2)	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	19, 69, 77
18Ch	EECON1	EEPGD	—	—	FREE	WRERR	WREN	WR	RD	x--x x000	28, 34
18Dh	EECON2	EEPROM Control Register 2 (not a physical register)								---- ----	34
18Eh	—	Reserved, maintain clear								0000 0000	—
18Fh	—	Reserved, maintain clear								0000 0000	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for PC<12:8>, whose contents are transferred to the upper byte of the program counter.

2: These registers can be addressed from any bank.

3: RA5 is an input only; the state of the TRISA5 bit has no effect and will always read '1'.

4: PIC16F88 device only.

2.2.2.1 STATUS Register

The STATUS register, shown in Register 2-1, contains the arithmetic status of the ALU, the Reset status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as '`000u u1uu`' (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions not affecting any Status bits, see **Section 16.0 "Instruction Set Summary"**.

Note:	The C and DC bits operate as a $\overline{\text{borrow}}$ and $\overline{\text{digit borrow}}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS: ARITHMETIC STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)
`1` = Bank 2, 3 (100h-1FFh)
`0` = Bank 0, 1 (00h-FFh)

bit 6-5 **RP<1:0>:** Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h-1FFh)
`10` = Bank 2 (100h-17Fh)
`01` = Bank 1 (80h-FFh)
`00` = Bank 0 (00h-7Fh)
Each bank is 128 bytes.

bit 4 **$\overline{TO}$:** Time-out bit
`1` = After power-up, `CLRWDT` instruction or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-Down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW` and `SUBWF` instructions)**(1)**
`1` = A carry-out from the 4th low-order bit of the result occurred
`0` = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW` and `SUBWF` instructions)**(1,2)**
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note 1: For borrow, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand.
2: For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low-order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.7.3 SEC_RUN/RC_RUN TO PRIMARY CLOCK SOURCE

When switching from a SEC_RUN or RC_RUN mode back to the primary system clock, following a change of SCS<1:0> to '00', the sequence of events that takes place will depend upon the value of the FOSC bits in the Configuration register. If the primary clock source is configured as a crystal (HS, XT or LP), then the transition will take place after 1024 clock cycles. This is necessary because the crystal oscillator has been powered down until the time of the transition. In order to provide the system with a reliable clock when the changeover has occurred, the clock will not be released to the changeover circuit until the 1024 count has expired.

During the oscillator start-up time, the system clock comes from the current system clock. Instruction execution and/or peripheral operation continues using the currently selected oscillator as the CPU clock source, until the necessary clock count has expired, to ensure that the primary system clock is stable.

To know when the OST has expired, the OSTS bit should be monitored. OSTS = 1 indicates that the Oscillator Start-up Timer has timed out and the system clock comes from the primary clock source.

Following the oscillator start-up time, the internal Q clocks are held in the Q1 state until eight falling edge clocks are counted from the primary system clock. The clock input to the Q clocks is then released and operation resumes with the primary system clock determined by the FOSC bits (see Figure 4-10).

When in SEC_RUN mode, the act of clearing the T1OSCEN bit in the T1CON register will cause SCS<0> to be cleared, which causes the SCS<1:0> bits to revert to '00' or '10' depending on what SCS<1> is. Although the T1OSCEN bit was cleared, T1OSC will be enabled and instruction execution will continue until the OST time-out for the main system clock is complete. At that time, the system clock will switch from the T1OSC to the primary clock or the INTRC. Following this, the T1 oscillator will be shut down.

Note:	If the primary system clock is either RC or EC, an internal delay timer (5-10 μs) will suspend operation after exiting Secondary Clock mode to allow the CPU to become ready for code execution.

4.7.3.1 Returning to Primary Clock Source Sequence

Changing back to the primary oscillator from SEC_RUN or RC_RUN can be accomplished by either changing SCS<1:0> to '00', or clearing the T1OSCEN bit in the T1CON register (if T1OSC was the secondary clock).

The sequence of events that follows is the same for both modes:

1. If the primary system clock is configured as EC, RC or INTRC, then the OST time-out is skipped. Skip to step 3.
2. If the primary system clock is configured as an external oscillator (HS, XT, LP), then the OST will be active, waiting for 1024 clocks of the primary system clock.
3. On the following Q1, the device holds the system clock in Q1.
4. The device stays in Q1 while eight falling edges of the primary system clock are counted.
5. Once the eight counts transpire, the device begins to run from the primary oscillator.
6. If the secondary clock was INTRC and the primary is not INTRC, the INTRC will be shut down to save current providing that the INTRC is not being used for any other function, such as WDT or Fail-Safe Clock monitoring.
7. If the secondary clock was T1OSC, the T1OSC will continue to run if T1OSCEN is still set; otherwise, the T1 oscillator will be shut down.

4.7.3.2 Returning to Primary Oscillator with a Reset

A Reset will clear SCS<1:0> back to '00'. The sequence for starting the primary oscillator following a Reset is the same for all forms of Reset, including POR. There is no transition sequence from the alternate system clock to the primary system clock on a Reset condition. Instead, the device will reset the state of the OSCCON register and default to the primary system clock. The sequence of events that takes place after this will depend upon the value of the FOSC bits in the Configuration register. If the external oscillator is configured as a crystal (HS, XT or LP), the CPU will be held in the Q1 state until 1024 clock cycles have transpired on the primary clock. This is necessary because the crystal oscillator has been powered down until the time of the transition.

During the oscillator start-up time, instruction execution and/or peripheral operation is suspended.

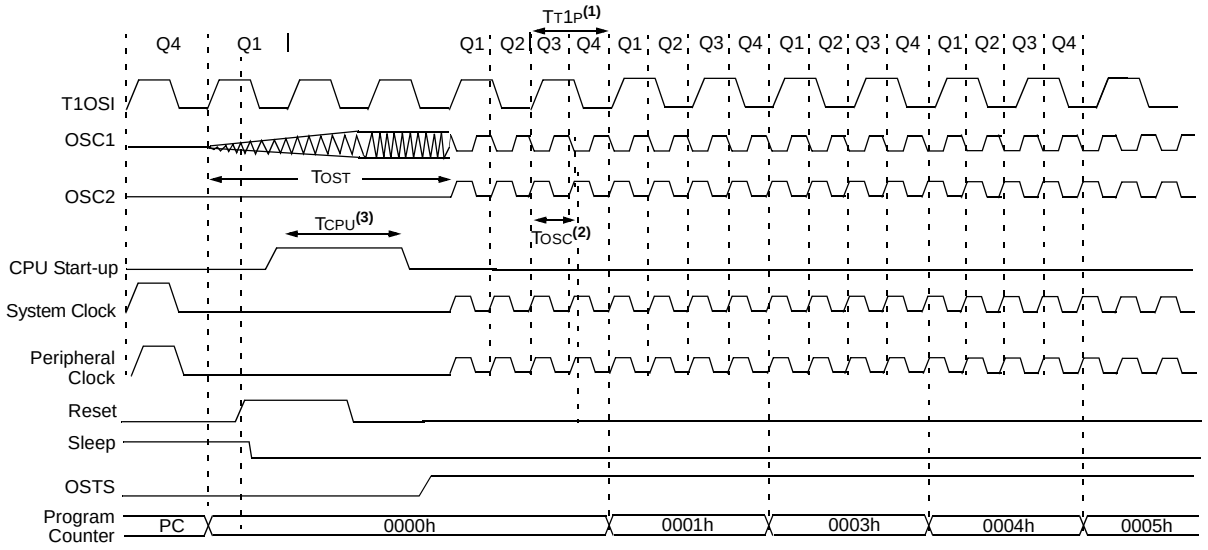
Note:	If Two-Speed Clock Start-up mode is enabled, the INTRC will act as the system clock until the OST timer has timed out.

If the primary system clock is either RC, EC or INTRC, the CPU will begin operating on the first Q1 cycle following the wake-up event. This means that there is no oscillator start-up time required because the primary clock is already stable; however, there is a delay between the wake-up event and the following Q2. An internal delay timer of 5-10 μs will suspend operation after the Reset to allow the CPU to become ready for code execution. The CPU and peripheral clock will be held in the first Q1.

The sequence of events is as follows:

1. A device Reset is asserted from one of many sources (WDT, BOR, MCLR, etc.).
2. The device resets and the CPU start-up timer is enabled if in Sleep mode. The device is held in Reset until the CPU start-up time-out is complete.
3. If the primary system clock is configured as an external oscillator (HS, XT, LP), then the OST will be active waiting for 1024 clocks of the primary system clock. While waiting for the OST, the device will be held in Reset. The OST and CPU start-up timers run in parallel.
4. After both the CPU start-up and OST timers have timed out, the device will wait for one additional clock cycle and instruction execution will begin.

FIGURE 4-10: PRIMARY SYSTEM CLOCK AFTER RESET (HS, XT, LP)



Note 1: TT1P = 30.52 μs.
2: TOSC = 50 ns minimum.
3: TCPU = 5-10 μs (1 MHz system clock).

7.2 Timer1 Operation in Timer Mode

Timer mode is selected by clearing the TMR1CS (T1CON<1>) bit. In this mode, the input clock to the timer is FOSC/4. The synchronize control bit, $\overline{\text{T1SYNC}}$ (T1CON<2>), has no effect since the internal clock is always in sync.

7.3 Timer1 Counter Operation

Timer1 may operate in Asynchronous or Synchronous mode, depending on the setting of the TMR1CS bit.

When Timer1 is being incremented via an external source, increments occur on a rising edge. After Timer1 is enabled in Counter mode, the module must first have a falling edge before the counter begins to increment.

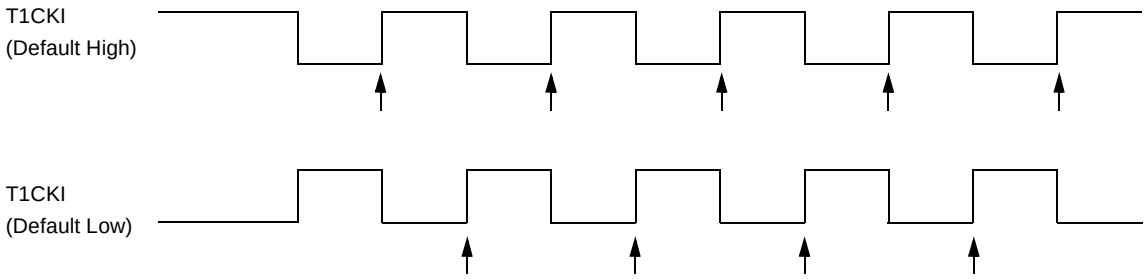
7.4 Timer1 Operation in Synchronized Counter Mode

Counter mode is selected by setting bit TMR1CS. In this mode, the timer increments on every rising edge of clock input on pin RB7/PGD/T1OSI when bit T1OSCEN is set, or on pin RB6/PGC/T1OSO/T1CKI when bit T1OSCEN is cleared.

If $\overline{\text{T1SYNC}}$ is cleared, then the external clock input is synchronized with internal phase clocks. The synchronization is done after the prescaler stage. The prescaler stage is an asynchronous ripple counter.

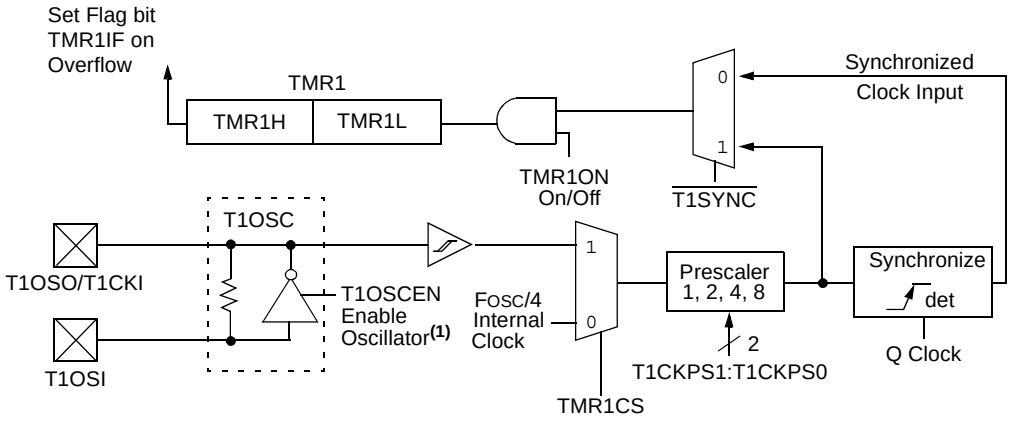
In this configuration, during Sleep mode, Timer1 will not increment even if the external clock is present since the synchronization circuit is shut off. The prescaler, however, will continue to increment.

FIGURE 7-1: TIMER1 INCREMENTING EDGE



Note: Arrows indicate counter increments.

FIGURE 7-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter is turned off. This eliminates power drain.

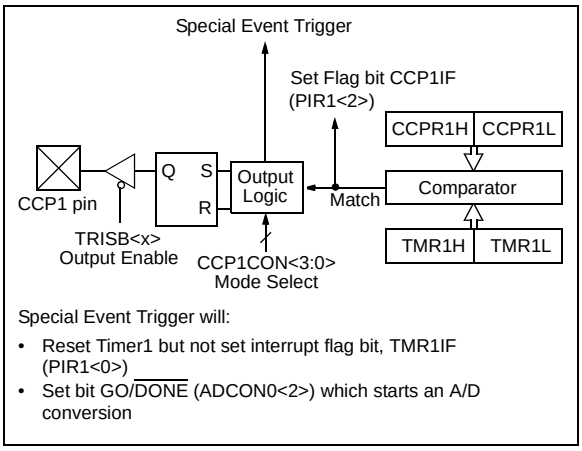
9.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the CCP1 pin is:

- Driven high
- Driven low
- Remains unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time, interrupt flag bit, CCP1IF, is set.

FIGURE 9-2: COMPARE MODE OPERATION BLOCK DIAGRAM



9.2.1 CCP PIN CONFIGURATION

The user must configure the CCP1 pin as an output by clearing the TRISB<x> bit.

Note 1:	Clearing the CCP1CON register will force the CCP1 compare output latch to the default low level. This is not the data latch.
2:	The TRISB bit (0 or 3) is dependent upon the setting of configuration bit 12 (CCPMX).

9.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

9.2.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

9.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated that may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair and starts an A/D conversion (if the A/D module is enabled). This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

Note:	The special event trigger from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

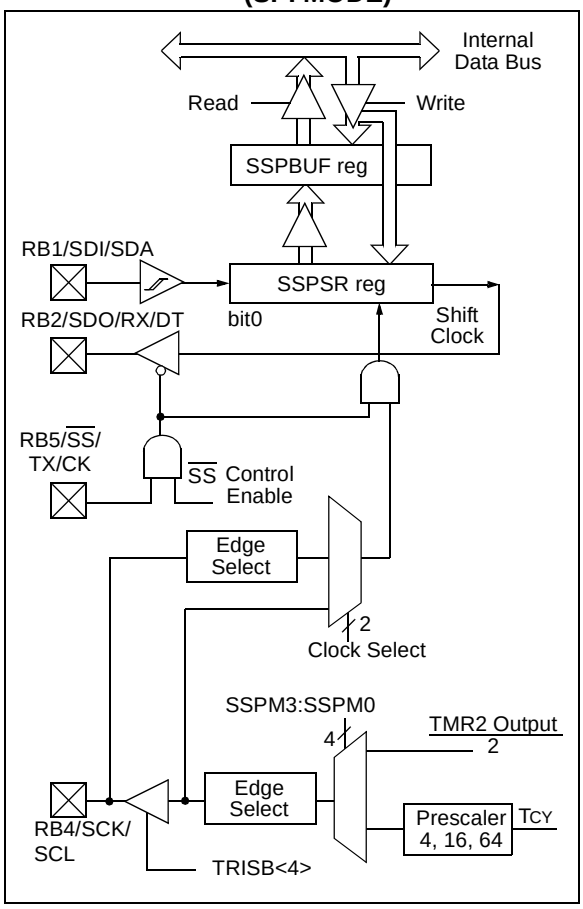
TABLE 9-2: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Bh,8Bh 10BH,18Bh	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF(1)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
8Ch	PIE1	—	ADIE(1)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	-000 0000	-uuu uuuu
15h	CCPR1L	Capture/Compare/PWM Register 1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register 1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by Capture and Timer1.

Note 1: This bit is only implemented on the PIC16F88. The bit will read '0' on the PIC16F87.

FIGURE 10-1: SSP BLOCK DIAGRAM (SPI MODE)



To enable the serial port, SSP Enable bit, SSPEN (SSPCON<5>), must be set. To reset or reconfigure SPI mode, clear bit SSPEN, reinitialize the SSPCON register and then set bit SSPEN. This configures the SDI, SDO, SCK and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRISB register) appropriately programmed. That is:

- SDI must have TRISB<1> set
- SDO must have TRISB<2> cleared
- SCK (Master mode) must have TRISB<4> cleared
- SCK (Slave mode) must have TRISB<4> set
- $\overline{SS}$ must have TRISB<5> set

Note 1: When the SPI is in Slave mode with $\overline{SS}$ pin control enabled (SSPCON<3:0> = 0100), the SPI module will reset if the $\overline{SS}$ pin is set to VDD.

2: If the SPI is used in Slave mode with CKE = 1, then the $\overline{SS}$ pin control must be enabled.

TABLE 10-1: REGISTERS ASSOCIATED WITH SPI OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF(1)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
8Ch	PIE1	—	ADIE(1)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the SSP in SPI mode.

Note 1: This bit is only implemented on the PIC16F88. The bit will read '0' on the PIC16F87.

13.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with I/O port pins RA0 through RA3, while the outputs are multiplexed to pins RA3 and RA4. The on-chip Voltage Reference (**Section 14.0 "Comparator Voltage Reference Module"**) can also be an input to the comparators.

The CMCON register (Register 13-1) controls the comparator input and output multiplexors. A block diagram of the various comparator configurations is shown in Figure 13-1.

REGISTER 13-1: CMCON: COMPARATOR MODULE CONTROL REGISTER (ADDRESS 9Ch)

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT:** Comparator 2 Output bit

When C2INV = 0:
1 = C2 V_{IN}+ > C2 V_{IN}-
0 = C2 V_{IN}+ < C2 V_{IN}-

When C2INV = 1:
1 = C2 V_{IN}+ < C2 V_{IN}-
0 = C2 V_{IN}+ > C2 V_{IN}-

bit 6 **C1OUT:** Comparator 1 Output bit

When C1INV = 0:
1 = C1 V_{IN}+ > C1 V_{IN}-
0 = C1 V_{IN}+ < C1 V_{IN}-

When C1INV = 1:
1 = C1 V_{IN}+ < C1 V_{IN}-
0 = C1 V_{IN}+ > C1 V_{IN}-

bit 5 **C2INV:** Comparator 2 Output Inversion bit

1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV:** Comparator 1 Output Inversion bit

1 = C1 output inverted
0 = C1 output not inverted

bit 3 **CIS:** Comparator Input Switch bit

When CM2:CM0 = 001:
1 = C1 V_{IN}- connects to RA3
0 = C1 V_{IN}- connects to RA0

When CM2:CM0 = 010:
1 = C1 V_{IN}- connects to RA3
C2 V_{IN}- connects to RA2
0 = C1 V_{IN}- connects to RA0
C2 V_{IN}- connects to RA1

bit 2-0 **CM<2:0>:** Comparator Mode bits

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

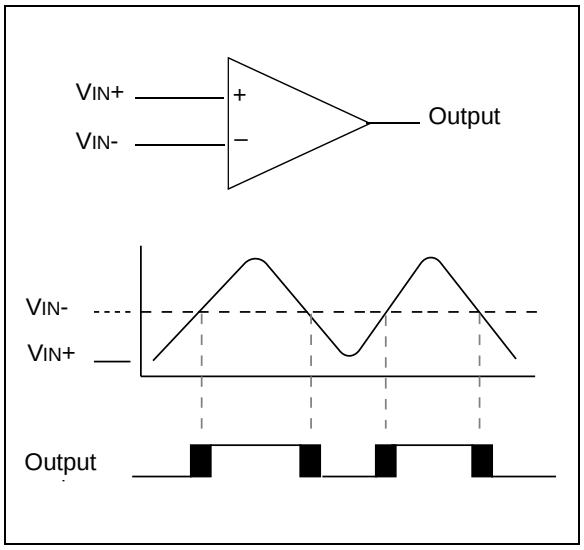
13.2 Comparator Operation

A single comparator is shown in Figure 13-2, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 13-2 represent the uncertainty due to input offsets and response time.

13.3 Comparator Reference

An external or internal reference signal may be used depending on the comparator operating mode. The analog signal present at VIN- is compared to the signal at VIN+ and the digital output of the comparator is adjusted accordingly (Figure 13-2).

FIGURE 13-2: SINGLE COMPARATOR



13.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same, or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD and can be applied to either pin of the comparator(s).

13.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. **Section 14.0 "Comparator Voltage Reference Module"** contains a detailed description of the Comparator Voltage Reference module that provides this signal. The internal reference signal is used when comparators are in mode CM<2:0> = 010 (Figure 13-1). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

13.4 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise, the maximum delay of the comparators should be used (**Section 18.0 "Electrical Characteristics"**).

13.5 Comparator Outputs

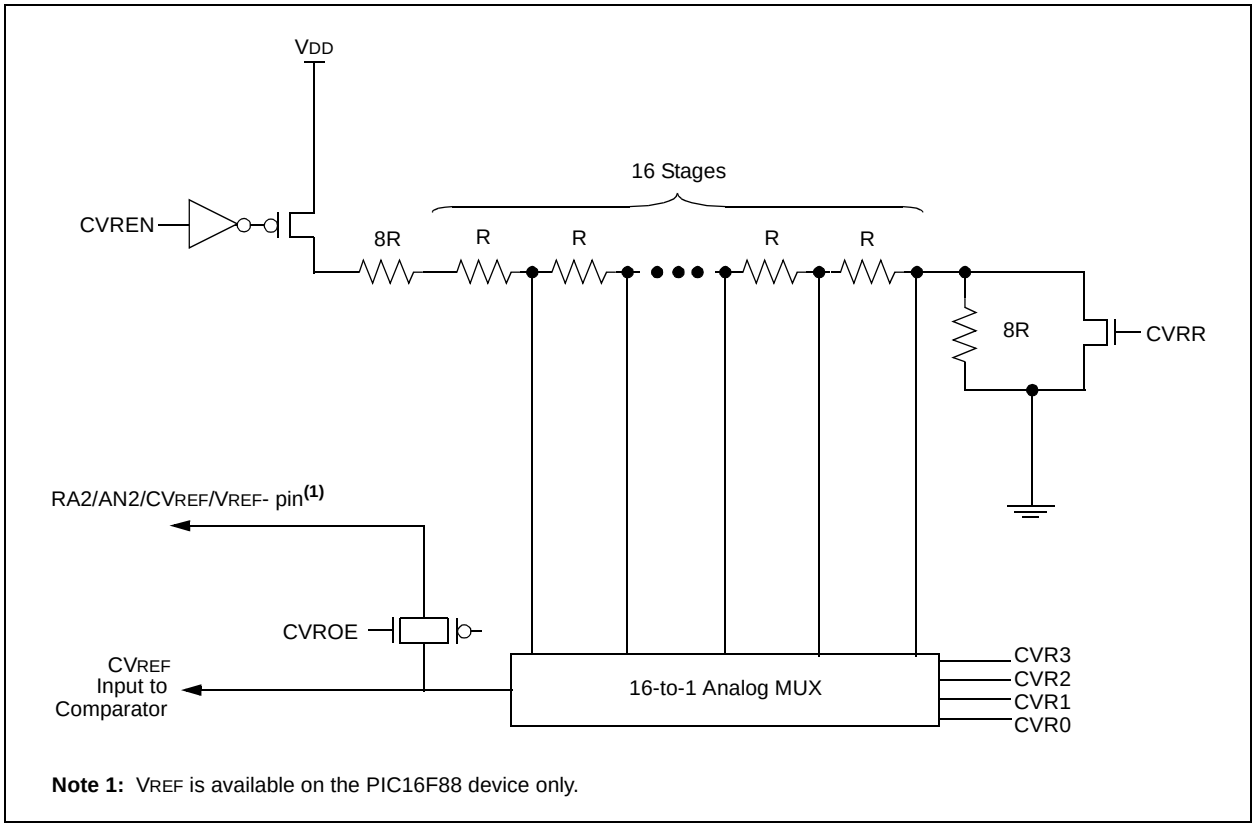
The comparator outputs are read through the CMCON register. These bits are read-only. The comparator outputs may also be directly output to the RA3 and RA4 I/O pins. When enabled, multiplexors in the output path of the RA3 and RA4 pins will switch and the output of each pin will be the unsynchronized output of the comparator. The uncertainty of each of the comparators is related to the input offset voltage and the response time given in the specifications. Figure 13-3 shows the comparator output block diagram.

The TRISA bits will still function as an output enable/ disable for the RA3 and RA4 pins while in this mode.

The polarity of the comparator outputs can be changed using the C2INV and C1INV bits (CMCON<5:4>).

Note 1:	When reading the Port register, all pins configured as analog inputs will read as '0'. Pins configured as digital inputs will convert an analog input, according to the Schmitt Trigger input specification.
2:	Analog levels, on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

FIGURE 14-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



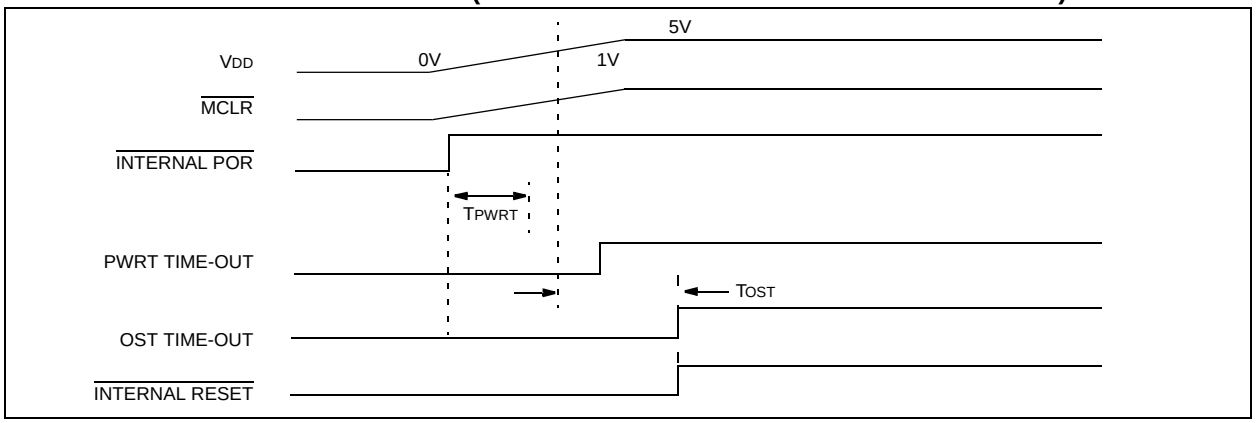
Note 1: VREF is available on the PIC16F88 device only.

TABLE 14-1: REGISTERS ASSOCIATED WITH COMPARATOR VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on all other Resets
9Dh	CVRCON	CVREN	CVROE	CVRR	—	CVR3	CVR2	CVR1	CVR0	000- 0000	000- 0000
9Ch	CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	0000 0111	0000 0111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used with the comparator voltage reference.

FIGURE 15-6: SLOW RISE TIME (MCLR TIED TO VDD THROUGH RC NETWORK)



15.10 Interrupts

The PIC16F87/88 has up to 12 sources of interrupt. The Interrupt Control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>), enables (if set) all unmasked interrupts, or disables (if cleared) all interrupts. When bit GIE is enabled and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on Reset.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine, as well as sets the GIE bit which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the Special Function Register, PIR1. The corresponding interrupt enable bits are contained in Special Function Register, PIE1 and the peripheral interrupt enable bit is contained in Special Function Register, INTCON.

When an interrupt is serviced, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends on when the interrupt event occurs, relative to the current Q cycle. The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit, PEIE bit or the GIE bit.

16.2 Instruction Descriptions

ADDLW	Add Literal and W
Syntax:	[*label*] ADDLW k
Operands:	$0 \le k \le 255$
Operation:	$(W) + k \rightarrow (W)$
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight-bit literal 'k' and the result is placed in the W register.

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(W) + (f) \rightarrow$ (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' = 0, the result is stored in the W register. If 'd' = 1, the result is stored back in register 'f'.

ANDLW	AND Literal with W
Syntax:	[*label*] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .AND. $(k) \rightarrow (W)$
Status Affected:	Z
Description:	The contents of W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .AND. $(f) \rightarrow$ (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' = 0, the result is stored in the W register. If 'd' = 1, the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$0 \rightarrow$ (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$1 \rightarrow$ (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

18.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... -0.3 to +14V
Total power dissipation **(Note 1)** 1W
Maximum current out of V_{SS} pin ..... 200 mA
Maximum current into V_{DD} pin ..... 200 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA ..... 100 mA
Maximum current sourced by PORTA ..... 100 mA
Maximum current sunk by PORTB ..... 100 mA
Maximum current sourced by PORTB ..... 100 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

2: Voltage spikes at the $\overline{MCLR}$ pin may cause latch-up. A series resistor of greater than 1 kΩ should be used to pull $\overline{MCLR}$ to V_{DD}, rather than tying the pin directly to V_{DD}.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

18.2 DC Characteristics: Power-Down and Supply Current PIC16F87/88 (Industrial, Extended) PIC16LF87/88 (Industrial) (Continued)

PIC16LF87/88 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC16F87/88 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD)(2,3)						
	PIC16LF87/88	72	95	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (RC Oscillator)(3)
		76	90	µA	+25°C		
		76	90	µA	+85°C		
	PIC16LF87/88	138	175	µA	-40°C	VDD = 3.0V	
		136	170	µA	+25°C		
		136	170	µA	+85°C		
	All devices	310	380	µA	-40°C	VDD = 5.0V	
		290	360	µA	+25°C		
		280	360	µA	+85°C		
	Extended devices	330	500	µA	125°C		
	PIC16LF87/88	270	335	µA	-40°C	VDD = 2.0V	FOSC = 4 MHz (RC Oscillator)(3)
		280	330	µA	+25°C		
		285	330	µA	+85°C		
	PIC16LF87/88	460	610	µA	-40°C	VDD = 3.0V	
		450	600	µA	+25°C		
		450	600	µA	+85°C		
	All devices	900	1060	µA	-40°C	VDD = 5.0V	
		890	1050	µA	+25°C		
		890	1050	µA	+85°C		
	Extended devices	.920	1.5	mA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

18.2 DC Characteristics: Power-Down and Supply Current PIC16F87/88 (Industrial, Extended) PIC16LF87/88 (Industrial) (Continued)

PIC16LF87/88 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC16F87/88 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2,3)						
	PIC16LF87/88	8	20	µA	-40°C	VDD = 2.0V	FOSC = 31.25 kHz (**RC_RUN** mode, Internal RC Oscillator)
		7	15	µA	+25°C		
		7	15	µA	+85°C		
	PIC16LF87/88	16	30	µA	-40°C	VDD = 3.0V	
		14	25	µA	+25°C		
		14	25	µA	+85°C		
	All devices	32	40	µA	-40°C	VDD = 5.0V	
		29	35	µA	+25°C		
		29	35	µA	+85°C		
	Extended devices	35	45	µA	+125°C		
	PIC16LF87/88	132	160	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_RUN** mode, Internal RC Oscillator)
		126	155	µA	+25°C		
		126	155	µA	+85°C		
	PIC16LF87/88	260	310	µA	-40°C	VDD = 3.0V	
		230	300	µA	+25°C		
		230	300	µA	+85°C		
	All devices	560	690	µA	-40°C	VDD = 5.0V	
		500	650	µA	+25°C		
		500	650	µA	+85°C		
	Extended devices	570	710	µA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 18-10: SPI MASTER MODE TIMING (CKE = 0, SMP = 0)

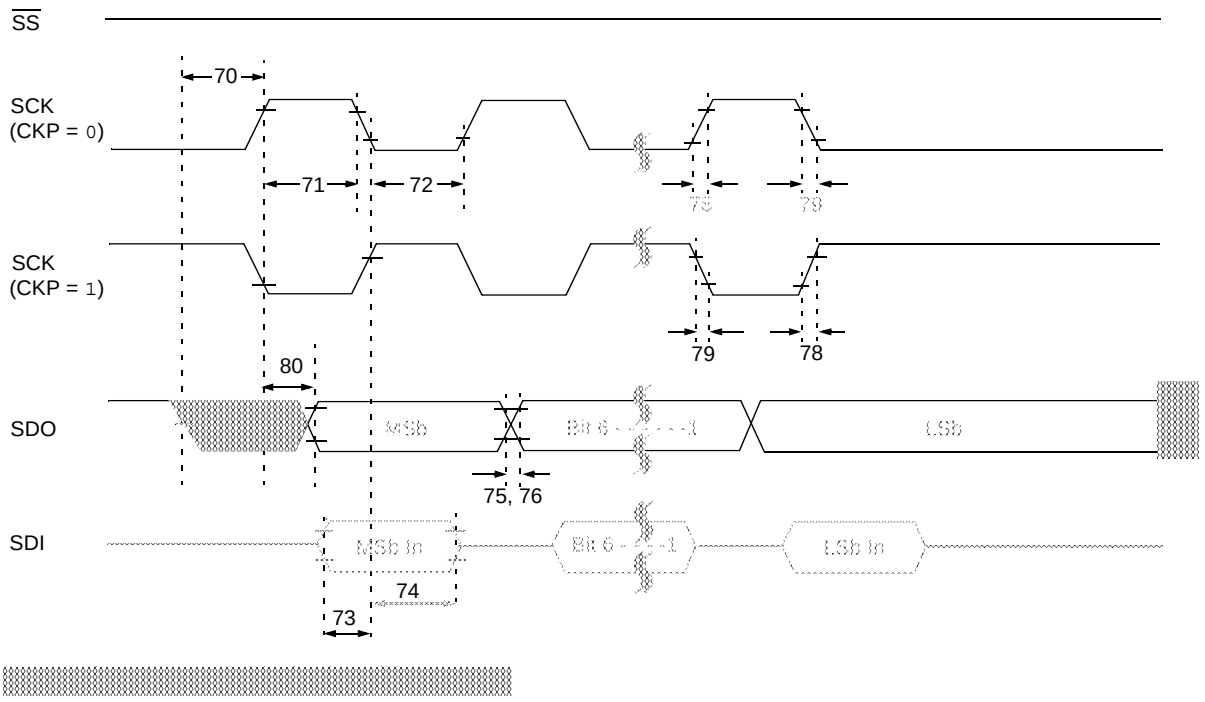
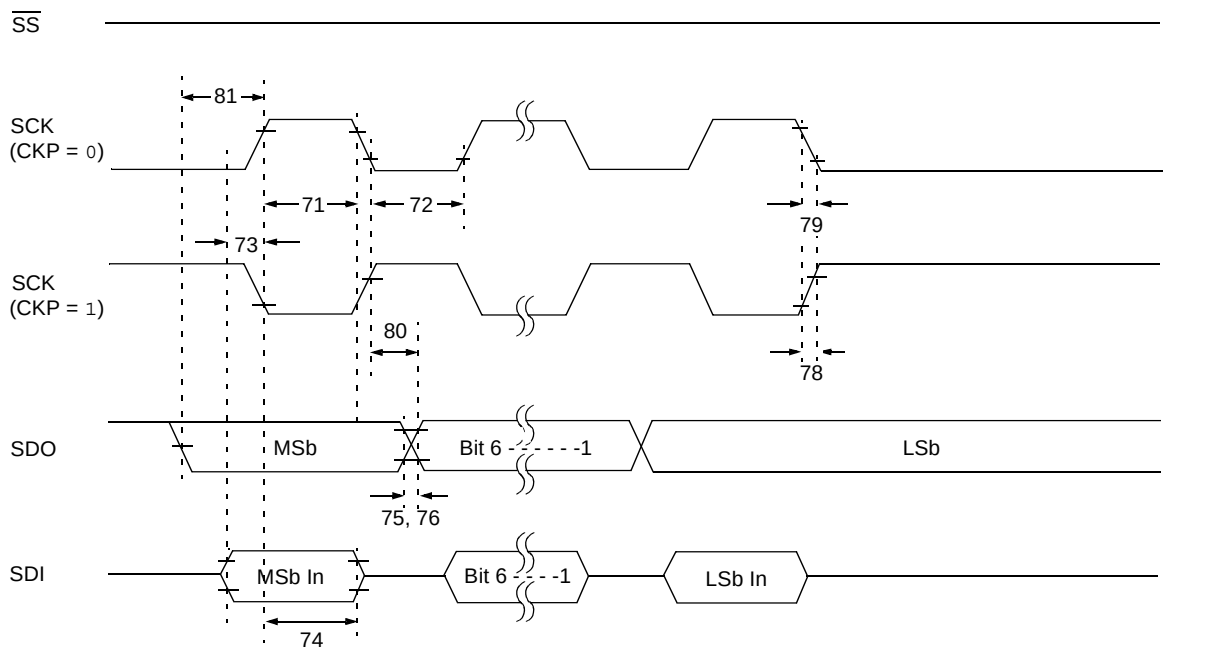


FIGURE 18-11: SPI MASTER MODE TIMING (CKE = 1, SMP = 1)



Note: Refer to Figure 18-3 for load conditions.

TABLE 18-13: A/D CONVERTER CHARACTERISTICS: PIC16F87/88 (INDUSTRIAL, EXTENDED) PIC16LF87/88 (INDUSTRIAL)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	10-bit	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral Linearity Error		—	—	<±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential Linearity Error		—	—	<±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset Error		—	—	<±2	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A07	EGN	Gain Error		—	—	<±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity		—	guaranteed(3)	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference Voltage (VREF+ – VREF-)		2.0	—	VDD + 0.3	V	
A21	VREF+	Reference Voltage High		AVDD – 2.5V		AVDD + 0.3V	V	
A22	VREF-	Reference Voltage Low		AVSS – 0.3V		VREF+ – 2.0V	V	
A25	VAIN	Analog Input Voltage		VSS – 0.3V	—	VREF + 0.3V	V	
A30	ZAIN	Recommended Impedance of Analog Voltage Source		—	—	2.5	kΩ	**(Note 4)**
A40	IAD	A/D Conversion Current (VDD)	PIC16F87/88	—	220	—	μA	Average current consumption when A/D is on **(Note 1)**
			PIC16LF87/88	—	90	—	μA	
A50	IREF	VREF Input Current **(Note 2)**		—	—	5	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see **Section 12.1 "A/D Acquisition Requirements"**.
				—	—	150	μA	During A/D conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current specification includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

4: Maximum allowed impedance for analog voltage source is 10 kΩ. This requires higher acquisition time.

FIGURE 19-11: AVERAGE FOSC vs. VDD FOR VARIOUS VALUES OF R (RC MODE, C = 20 pF, +25°C)

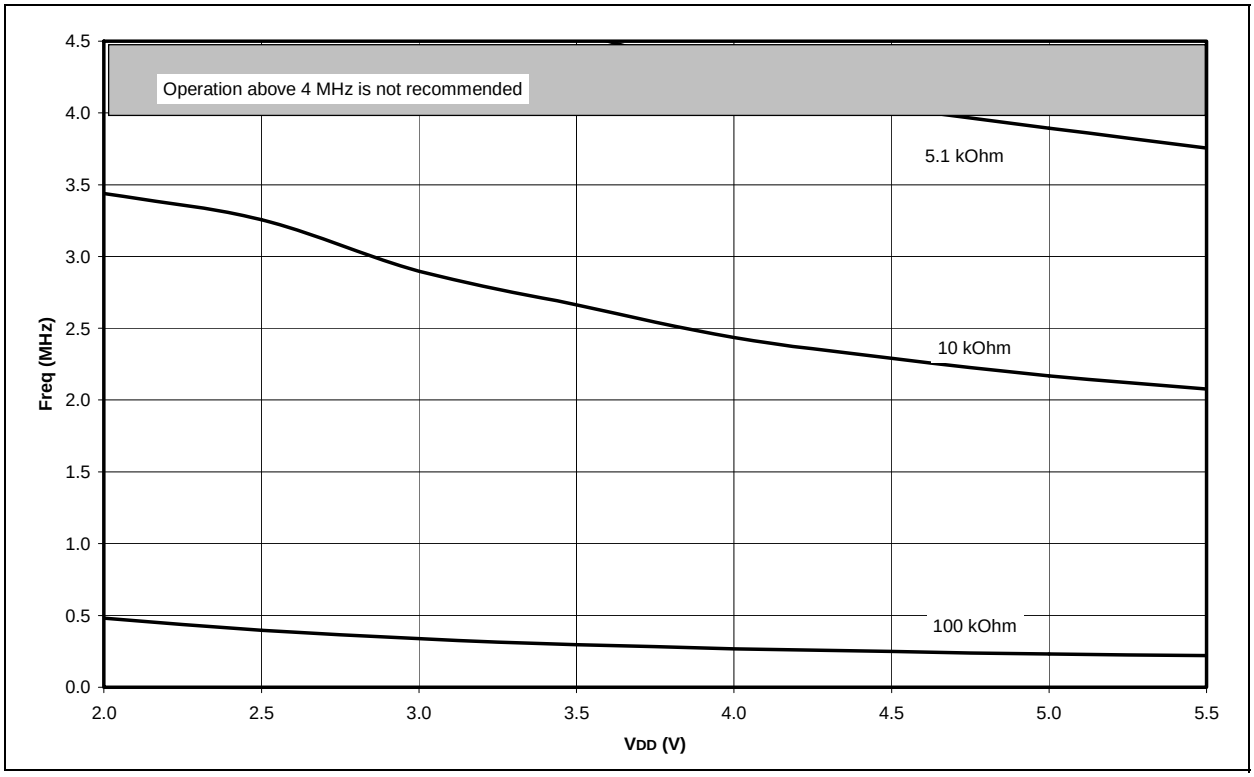


FIGURE 19-12: AVERAGE FOSC vs. VDD FOR VARIOUS VALUES OF R (RC MODE, C = 100 pF, +25°C)